## **BRAC** University **Department of Computer Science and Engineering**

**Final Exam** 

Semester: Summer 2024 Course Code: CSE460 Course Title: VLSI Design

Full Marks:  $15 \times 3 = 45$ Time: 1 hour 40 minutes Date: 28th September 2024

## Set A

Student ID:	Name:	Section:
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[Answer any THREE questions out of FOUR. Each question carries 15 marks. Return the question paper with the answer script.]

1. (CO4) An initial cut for a partition of 8 circuit elements (a, b, c, d, e, f, g, and h) is given in Figure 1.

> The cut line divides the circuit elements into two partitions named A and B.

> (a) Calculate the initial cut cost, and the cost of [1] moving each node.

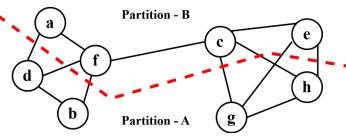


Figure 1

- (b) Perform the first pass of the algorithm. For every "i"th iteration inside the first pass, until all the nodes are swapped and fixed, do the following:
  - i. Compute the node costs of all unfixed nodes
  - ii. Find the maximum gain of swapping a pair of nodes  $(\Delta \mathbf{g_i})$
  - iii. Swap the pair and draw the updated graph
- (c) Compute  $G_i$  of each iteration and find the maximum  $G_i = G_m$ . Suggest how many swaps should be actually executed in the first pass. Redraw the optimized graph.
- (d) Should you perform subsequent passes of the algorithm? Why or why not?

[1]

[4]

[9]

2. (CO1) Brook is a chip designer who works specifically on the  $\lambda = 1.5 \,\mu m$  process. However, he has messed up the layout design of a 3-input NOR gate (Figure 2(a)) because of which, the NOR gate has an equivalent rise resistance that is four times its equivalent fall resistance. Also, the NOR gate's equivalent rise resistance is twice the rise resistance of a unit inverter for that design process. But at least he made sure to keep the source-drain terminals shared where possible to reduce capacitance. The gate capacitance and parasitic (diffusion) capacitance of are 0.5 fF/μm.

> This NOR gate is loaded with a Unit inverter and the output node Y has a voltage waveform as shown in Fig. 2(c).

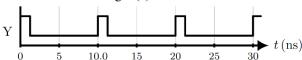


Figure 2(c): Voltage waveform at node Y

(a) Find the value of width scaling factors -  $k_p$  and  $k_n$  of the NOR gate designed by Brook. Thereafter, calculate the actual width of the pMOS and Figure 2(b): A 3-input NOR gate loaded nMOS. [2]

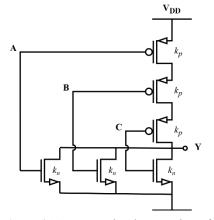
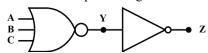


Figure 2(a): CMOS implementation of a 3 - input NOR gate



with a Unit Inverter

- (b) Draw the RC equivalent model of the above 3-input NOR gate. Lump the capacitances together where possible. [5]
- (c) Find the capacitance of the Y node (in fF units), when it is loaded with a unit inverter, as shown in Fig. 2(b).
- (d) Find the worst-case falling edge propagation delay  $(t_{pdf})$  of Y-node in terms of R and C the equivalent resistance and capacitance of a unit sized MOS. [Hint: You do not need Elmore modelling.]
- (e) Find the switching power of the Y-node, if the system has a supply voltage of 5 V.

[3]

[2]

[2]

3. (CO4)	For question (a) you are given a certain <b>chip planning task.</b> You have three blocks with the following widths and heights:		
	<b>Block A:</b> $w = 2$ , $h = 3$ or $w = 3$ , $h = 2$ <b>Block B:</b> $w = 1$ , $h = 2$ or $w = 2$ , $h = 1$ <b>Block C:</b> $w = 1$ , $h = 4$ or $w = 4$ , $h = 1$	S T1 Obstacle	
	For questions (b-e) refer to the adjacent figures on the right of the paper, you can see the grid layout of a system with a source $(S)$ and two targets $-T1$ and $T2$ . The obstacles and free cells are shown.	Free Cell	
	(a) <b>Define</b> chip planning. <b>Find</b> and draw a floorplan with the minimum [3] total area enclosed by its global bounding box.		
	<ul> <li>(b) Using the Lee's Maze Algorithm, find the shortest path from S to T1 [4] and T2 allowing minimum bends.</li> <li>Answer this question on the grids on the question paper.</li> </ul>	S	
	(c) Find the total memory usage of the given grid if the sequence is a [3] series of natural numbers.	T1 Obstacle	
	(d) If the maximum memory requirement of the provided grid is 36 bytes, [3] calculate the maximum number of bits that each cell can hold.	<del>                                     </del>	
	(e) Find the number of consecutive and unique numbers (starting from 1) [2] that can be used for wave propagation in the Lee's Maze algorithm, for the given memory constraint.	S	,
	What should be a full sequence for wave propagation?	T1	
4. (CO1)	Suppose the technology you are using to design a VLSI system has $\lambda = 80$ nm, a clock frequency of <b>5 MHz</b> , and a supply is <b>5 V</b> . The chip you are designing has <b>5 million transistors</b> , of which <u>1 million</u> remain <b>active</b> at any given time. The activity factor is defined by the fraction of total components which remain active. The gate and diffusion capacitances are 12 fF/ $\mu$ m and 5 fF/ $\mu$ m, respectively for all the 5 million transistors. The gate width is <b>20</b> $\lambda$ . You also obtain the following power consumption data:	T2 Free Cell	
	<ul> <li>Short circuit power = 0.5 W</li> <li>Leakage power = 0.01 W</li> <li>Subthreshold power = 0.02 W</li> </ul>		
	The acceptable TOTAL power consumption of a chip is 3 W.		
	(a) Find the activity factor and load capacitance of the system described about	ove. [	2]
	<b>(b)</b> Calculate the switching power consumption of the chip.	[:	3]
	(c) Calculate the dynamic and static power of the chip. Thereafter calculate the TOTAL power consumption. [3		
	(d) Is the <b>TOTAL</b> power consumption within the acceptable range? If not, it keep the <b>TOTAL</b> power within the acceptable range?	find the maximum clock frequency to	4]
	(e) For a 10-input NAND gate, what should be the ratio of width scaling fa	ectors $-k_p/k_n$ - for the NMOS and PMOS [	3]

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## Set B

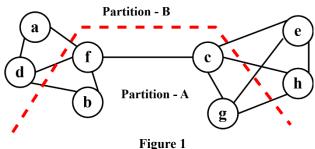
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[Answer any THREE questions out of FOUR. Each question carries 15 marks. Return the question paper with the answer script.]

1. (CO4) An initial cut for a partition of 8 circuit elements (a, b, c, d, e, f, g, and h) is given in Figure 1.

The cut line divides the circuit elements into two partitions named A and B.

(a) Calculate the initial cut cost, and the cost of moving each node. [1]



- **(b) Perform** the first pass of the algorithm. For every "i"th iteration inside the first pass, until all the nodes are swapped and fixed, do the following:
  - i. Compute the node costs of all unfixed nodes
  - ii. Find the maximum gain of swapping a pair of nodes  $(\Delta \mathbf{g_i})$
  - iii. Swap the pair and draw the updated graph
- (c) Compute  $G_i$  of each iteration and find the maximum  $G_i = G_m$ . Suggest how many swaps should be actually executed in the first pass. Redraw the optimized graph.
- (d) Should you perform subsequent passes of the algorithm? Why or why not?

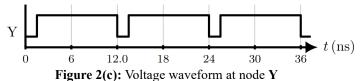
[1]

[4]

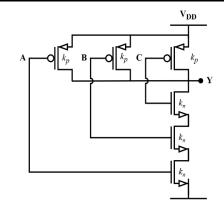
[9]

2. (CO1) Bob is a chip designer who works specifically on the λ = 0.25 μm process. However, he has messed up the layout design of a 3-input NAND gate (Figure 2(a)) because of which, the NAND gate has an equivalent rise resistance that is four times its equivalent fall resistance. Also, the NAND gate's equivalent rise resistance is 1.5 the rise resistance of a unit inverter for that design process. But at least he made sure to keep the source-drain terminals shared where possible to reduce capacitance. The gate capacitance and parasitic (diffusion) capacitance of are 2.42 fF/μm.

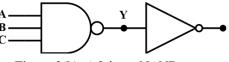
This **NOR gate** is loaded with a **Unit inverter** and the output node **Y** has a voltage waveform as shown in Fig. 2(c).



(a) Find the value of width scaling factors -  $k_p$  and  $k_n$  of the NOR gate designed by Bob. Thereafter, calculate the actual width of the pMOS and nMOS. [2]



**Figure 2(a):** CMOS implementation of a 3 - input NAND gate



**Figure 2(b):** A 3-input NAND gate loaded with a **Unit Inverter** 

- (b) Draw the RC equivalent model of the above 3-input NAND gate. Lump the capacitances together where possible. [5]
- (c) Find the capacitance of the Y node (in fF units), when it is loaded with a unit inverter, as shown in Fig. 2(b).
- (d) Find the worst-case <u>rising</u> edge **propagation delay**  $(t_{pdr})$  of **Y**-node in terms of **R** and **C** the equivalent resistance and capacitance of a unit sized MOS. [Hint: You do not need Elmore modelling.]
- (e) Find the switching power of the Y-node, if the system has a supply voltage of 3.3 V.

[3]

[2]

[2]

3. (CO4)	For question (a) you are given a certain <b>chip planning task.</b> You have three blocks with the following widths and heights:				
	<b>Block A:</b> $w = 1$ , $h = 4$ or $w = 4$ , $h = 1$ <b>Block B:</b> $w = 1$ , $h = 2$ or $w = 2$ , $h = 1$ <b>Block C:</b> $w = 2$ , $h = 3$ or $w = 3$ , $h = 2$	T1 S S Obstacle			
	For questions (b-e) refer to the adjacent figures on the right of the paper, you can see the grid layout of a system with a source (S) and two targets – T1 and T2. The obstacles and free cells are shown.	Free Cell	[		
	(a) <b>Define</b> chip planning. <b>Find</b> and draw a floorplan with the minimum [3] total area enclosed by its <u>global bounding box</u> .				
	<ul> <li>(b) Using the Lee's Maze Algorithm, find the shortest path from S to T1 [4] and T2 allowing minimum bends.</li> <li>Answer this question on the grids on the question paper.</li> </ul>	T1			
	(c) Find the total memory usage of the given grid if the sequence is a [3] series of natural numbers.	S			
	(d) If the maximum memory requirement of the provided grid is 24 bytes, [3] calculate the maximum number of bits that each cell can hold.	Free Cell	[		
	(e) Find the number of consecutive and unique numbers (starting from 1) [2] that can be used for wave propagation in the Lee's Maze algorithm, for the given memory constraint.	T1			
	What should be a full sequence for wave propagation?	S			
4. (CO1)	Suppose the technology you are using to design a VLSI system has $\lambda = 40$ nm, a clock frequency of 2.5 MHz, and a supply is 5 V. The chip you are designing has 10 million transistors, of which 4 million remain active at any given time. The activity factor is defined by the fraction of total components which remain active. The gate and diffusion capacitances are 12 fF/ $\mu$ m and 5 fF/ $\mu$ m, respectively for all the 10 million transistors. The gate width is 20 $\lambda$ . You also obtain the following power consumption data:	Obstacle Free Cell			
	<ul> <li>Short circuit power = 0.5 W</li> <li>Leakage power = 0.01 W</li> <li>Subthreshold power = 0.02 W</li> </ul>				
	The acceptable TOTAL power consumption of a chip is 3 W.				
	(a) Find the activity factor and load capacitance of the system described abo	ve.	[2]		
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